

# Interfacing the DP8420A/21A/22A to the 29000 Utilizing the Burst Access Mode

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## INTRODUCTION

This application note describes how to interface the 29000 microprocessor to the DP8422A DRAM controller (also applicable to DP8420A/21A). The DP8422A supports the 29000 in the burst access mode. It is assumed that the reader is already familiar with 29000 access cycles and the DP8422A modes of operation.

### IA. Description of Designs #1 and #2, the 29000 in burst access mode on the instruction bus, allowing operation up to 25 MHz with four wait states in normal accesses and one or two wait states in burst accesses

The two designs of this application note consist of the DP8422A DRAM controller, a single PAL® (PAL16L8D), several flip-flops, and several logic gates. These parts interface to the 29000 as shown in the block diagrams. This design accommodates two banks of DRAM, each bank being 32 bits in width, giving a maximum memory capacity of 32 Mbytes (using 4M-bit X 1 DRAMs).

This memory design supports burst accesses by the 29000 to the instruction bus but could also support burst accessing to the data bus given a few minor changes. Design #1 inserts 4 wait states in normal accesses and 2 wait states in burst accesses. Design #2 inserts 4 wait states in normal accesses and 1 wait state in burst accesses. When idle states occur during a burst access the next occurring access will only have one wait state.

This application allows page mode DRAMs to be used by holding  $\overline{RAS}$  low after an access is completed ( $\overline{IRDY}$  low) until either a refresh request or a new access request ( $\overline{IREQ}$ ) is generated. If  $\overline{IBREQ}$  (Instruction Burst Request) has transitioned low the next sequential word is accessed from the DRAM via a page mode access. This access involves incrementing the column address (DP8422A COLINC input high) and toggling the  $\overline{CAS}$  outputs via the PAL  $\overline{ECAS}$  output. The instruction burst acknowledge ( $\overline{IBACK}$ ) input is driven low except in the case of a refresh request ( $\overline{RFRQ}$ ) or a new access ( $\overline{IREQ}$ ) being requested.

If the user wants to do dual accessing with the DP8422A DRAM controller, address buffers (74AS244s) must be added to the address,  $\overline{ECAS0-3}$ ,  $\overline{LOCK}$ , and  $\overline{WIN}$  inputs.

Note that the DP8422A DRAM controller could be used to allow instruction memory accessing thru Port A. The instruction memory could be loaded thru a data memory interface to Port B.

The logic shown in these applications form a complete 29000 memory sub-system, no other logic is needed. This sub-system automatically takes care of:

- A. arbitration between Port A, and refreshing the DRAM;
- B. the insertion of wait states to the processor (Port A) when needed;
- C. remaining in burst access mode unless a refresh request ( $\overline{RFRQ}$ ) or new instruction request is generated;
- D. incrementing the column address during burst mode accesses; and
- E. guaranteeing the  $\overline{RAS}$  and  $\overline{CAS}$  low and precharge times.

The timing calculations for this design are included in this application note.

When using the DP8420A/21A/22A at or above 20 MHz the user should program three clock periods of precharge. This is because two clock periods of precharge at 20 MHz will only guarantee 77 ns of  $\overline{RAS}$  precharge ( $2 \times 50 \text{ ns} - tD1$ , parameter #50 "14 ns" — clock (20 MHz) to  $\overline{AREQ}$  high "9 ns").

### IB. High Performance NO WAIT State 29000 System

A higher performance 29000 system (similar to the ones discussed in this application note) could be designed using the DP8422A by accessing four  $\overline{RAS}$  banks at once, this could allow zero wait state burst accesses. An example of this method using 2 DRAM banks is shown at the end of this application note. If 2 DRAM controllers were used (4 BANKs) burst accesses could execute in zero wait states. The COLINC inputs to the two DRAM controllers would be staggered in time as well as the four  $\overline{ECAS}$  outputs ( $\overline{B0ECAS-B3ECAS}$ ) from the 29000 control logic block.

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## II. 29000 Programming mode bits

Programming Bits	Description
R0 = 1 R1 = 1	$\overline{\text{RAS}}$ low four clocks, $\overline{\text{RAS}}$ precharge of three clocks
R2 = 1 R3 = 0	$\overline{\text{DTACK}}$ will be asserted on the positive edge of CLK following the access $\overline{\text{RAS}}$
R4 = 0 R5 = 0 R6 = X R7 = 1	No WAIT states during burst accesses  $\overline{\text{DTACK}}$ output
R8 = 1 R9 = X	Non-address pipelining to support burst accessing
C0 = X C1 = X C2 = X	Select based upon the input clock frequency. Example: if the DELCLK frequency is 20 MHz then choose C0,1,2 = 0,0,0 (divide by ten, this will give a frequency of 2 MHz).
C3 = X	
C4 = 0 C5 = 0 C6 = 1	$\overline{\text{RAS}}$ and $\overline{\text{CAS}}$ groups selected by "B1". This mode allows two $\overline{\text{RAS}}$ and four $\overline{\text{CAS}}$ outputs to go low during an access.
C7 = 1 C8 = 1	Column address setup time of 0 ns. Row address hold time of 15 ns
C9 = 1	Delay $\overline{\text{CAS}}$ during write accesses to one clock after $\overline{\text{RAS}}$ transitions low.
B0 = 0  B1 = 1	Latching of the address inputs, needed for the burst accessing capability of the 29000 (COLINC input in particular). Access mode 1

0 = Program with low voltage level  
1 = Program with high voltage level  
X = Program with either low voltage level (don't care condition)

### III. 29000 25 MHz timing calculations for Design #1 and Design #2, with four wait states per normal access and one or two wait states per burst access

- Maximum time to address valid (with respect to 25 MHz clock):  
14 ns (29000 data sheet #6)
- Maximum time to  $\overline{\text{ADS}}$  low (with respect to 25 MHz clock):  
9 ns (74AS374 clock to Q, tPHL)
- Minimum  $\overline{\text{ADS}}$  low setup time to CLK high (DP8422-25 needs 25 ns, #400b):  
40 ns (one clock period, 25 MHz) - 9 ns (#2) = 31 ns
- Minimum address setup time to  $\overline{\text{ADS}}$  low (DP8422-25 needs 14 ns, #404):  
40 ns (One clock period, 25 MHz) + 2 ns (minimum 74AS374 clock to Q) - 14 ns (#1) = 28 ns
- Minimum  $\overline{\text{CS}}$  setup time to CLKA high (DP8422-25 needs 5 ns, #401):  
24 ns (#4) - 9 ns (74AS138 decoder) = 15 ns
- Determining tRAC ( $\overline{\text{RAS}}$  access time needed by the DRAM):  
200 ns (five clock periods at 25 MHz) - 40 ns (one clock period, T1) - 9 ns (#2) - 6 ns (29000 data setup time, #9a) - 7 ns (74F245) - 29 ns (CLK to  $\overline{\text{RAS}}$  low) = 109 ns

Therefore the tRAC of the DRAM must be 109 ns or less.

- Determining tCAC ( $\overline{\text{CAS}}$  access time needed by the DRAM) and tAA (column address access time):

200 ns - 40 ns - 9 ns - 6 ns - 7 ns - 82 ns (CLK to  $\overline{\text{CAS}}$  low) = 56 ns

Therefore the tCAC and tAA (access time from the column address) of the DRAM must be 56 ns or less. COMMON 100 ns DRAMS WILL MEET THIS tRAC, tAA, AND tCAC PARAMETER.

- Minimum setup of  $\overline{\text{DTACK}}$ 1 to the 74AS374 ONLY, (need 2 ns):  
40 ns (one clock period) - 28 ns (DP8422A-25  $\overline{\text{DTACK}}$ 1 delay, #18) = 12 ns
- Minimum  $\overline{\text{IRDY}}$  setup time to  $\overline{\text{IRDY}}$  being sampled (12 ns is needed by the 29000, #9):  
40 ns (one clock period) - 9 ns (maximum 74AS374 clock to Q output delay) = 31 ns

10a. Determining tCAC during a burst access for Design #1:

120 ns (3 clock periods) – 20 ns (one half clock period during which  $\overline{CAS}$  is high) – 10 ns (PAL16L8 maximum propagation delay) – 12 ns (74AS32 propagation delay driving  $\approx 125$  pF with damping resistor and other associated delays) – 6 ns (data setup time) – 7 ns (74F245) = 65 ns

Therefore the tCAC of the DRAM must be  $\leq 65$  ns

10b. Determining tCAC during a burst access for Design #2:

80 ns (2 clock periods) – 20 ns (one half clock period during which  $\overline{CAS}$  is high) – 10 ns (PAL16L8 maximum propagation delay) – 12 ns (74AS32 propagation delay driving  $\approx 125$  pF with damping resistor and other associated delays) – 6 ns (data setup time) – 7 ns (74F245) = 25 ns

Therefore the tCAC of the DRAM must be  $\leq 25$  ns

11a. Determining tAA during a burst access for Design #1: 160 ns (4 clock periods, because  $\overline{IRDY}$  inverted is COLINC) – 39 ns (DP8422A COLINC to Q's valid, #27) = 121 ns  $\geq$  tAA.

11b. Determining tAA during a burst access for Design #2: 120 ns (3 clock periods, because  $\overline{IRDY}$  inverted is COLINC) – 39 ns (DP8422A COLINC to Q's valid, #27) = 81 ns  $\geq$  tAA.

#### IV. 29000 PAL equations, Design #1, 2 wait states during burst accesses. Written in National Semiconductor PLAN™ format

PAL16L8D

CLK  $\overline{CS}$   $\overline{IREQ}$   $\overline{IBREQ}$   $\overline{DTACK2}$   $\overline{AREQ}$   $\overline{IRDY}$   $\overline{IRDY3}$   $\overline{RFRQD}$   
GND RESET  $\overline{IBACK}$   $\overline{ECAS}$   $\overline{ECAS1}$   $\overline{DOACC}$   $\overline{ENDACC}$   $\overline{IREQH}$   
 $\overline{IRDY1}$   $\overline{AREQ1}$  VCC

If (VCC)  $\overline{IBACK} = \overline{AREQ} * \overline{RFRQD} * \overline{IREQH} * \overline{DTACK2}$   
+  $\overline{AREQ} * \overline{RFRQD} * \overline{IREQH} * \overline{IREQ}$   
+  $\overline{IBACK} * \overline{IREQH} * \overline{RFRQD}$

If (VCC)  $\overline{ECAS} = \overline{AREQ} * \overline{ECAS1} * \overline{DOACC} * \overline{RESET}$   
+  $\overline{AREQ} * \overline{DOACC} * \overline{IRDY3} * \overline{CLK} * \overline{RESET}$   
+  $\overline{AREQ} * \overline{DOACC} * \overline{IRDY1} * \overline{RESET}$   
+  $\overline{ECAS} * \overline{ECAS1} * \overline{CLK} * \overline{RESET}$   
+  $\overline{ECAS} * \overline{CLK} * \overline{RESET}$

If (VCC)  $\overline{ECAS1} = \overline{IRDY} * \overline{CLK}$   
+  $\overline{ECAS1} * \overline{CLK}$

If (VCC)  $\overline{DOACC} = \overline{AREQ} * \overline{RFRQD} * \overline{IBREQ} * \overline{RESET}$   
+  $\overline{CS} * \overline{IREQ} * \overline{IREQH} * \overline{AREQ} * \overline{RESET}$   
+  $\overline{DOACC} * \overline{IRDY} * \overline{RESET}$

If (VCC)  $\overline{ENDACC} = \overline{IREQ} * \overline{IREQH}$   
+  $\overline{RFRQD} * \overline{IRDY}$   
+  $\overline{RFRQD} * \overline{AREQ} * \overline{IREQH}$   
+  $\overline{ENDACC} * \overline{AREQ}$   
+  $\overline{RESET}$

If (VCC)  $\overline{IREQH} = \overline{AREQ} * \overline{IREQ}$   
+  $\overline{IREQH} * \overline{AREQ} * \overline{RESET}$

If (VCC)  $\overline{IRDY1} = \overline{DTACK2} * \overline{AREQ} * \overline{IRDY} * \overline{IRDY3} * \overline{IREQH}$   
+  $\overline{AREQ} * \overline{IRDY} * \overline{IRDY3} * \overline{IREQH} * \overline{CLK} * \overline{DOACC}$   
+  $\overline{IRDY1} * \overline{IRDY} * \overline{IRDY3} * \overline{AREQ}$

If (VCC)  $\overline{AREQ1} = \overline{CS} * \overline{IREQ} * \overline{IRDY} * \overline{ENDACC} * \overline{RESET}$   
+  $\overline{AREQ1} * \overline{ENDACC} * \overline{RESET}$   
+  $\overline{AREQ1} * \overline{DOACC} * \overline{RESET}$

#### 29000 PAL equations, Design #2, 1 wait state during burst accesses. Written in National Semiconductor PLAN format

PAL16L8D

CLK  $\overline{CS}$   $\overline{IREQ}$   $\overline{IBREQ}$   $\overline{DTACK2}$   $\overline{AREQ}$   $\overline{IRDY}$   $\overline{IRDY3}$   $\overline{RFRQD}$   
GND RESET  $\overline{IBACK}$   $\overline{ECAS}$   $\overline{ECAS1}$   $\overline{DOACC}$   $\overline{ENDACC}$   $\overline{IREQH}$   
 $\overline{IRDY1}$   $\overline{AREQ1}$  VCC

If (VCC)  $\overline{IBACK} = \overline{AREQ} * \overline{RFRQD} * \overline{IREQH} * \overline{DTACK2}$   
+  $\overline{AREQ} * \overline{RFRQD} * \overline{IREQH} * \overline{IREQ}$   
+  $\overline{IBACK} * \overline{IREQH} * \overline{RFRQD}$

If (VCC)  $\overline{ECAS} = \overline{AREQ} * \overline{ECAS1} * \overline{DOACC} * \overline{RESET}$   
+  $\overline{AREQ} * \overline{DOACC} * \overline{IRDY3} * \overline{CLK} * \overline{RESET}$   
+  $\overline{AREQ} * \overline{DOACC} * \overline{CLK} * \overline{RESET}$   
+  $\overline{ECAS} * \overline{ECAS1} * \overline{CLK} * \overline{RESET}$   
+  $\overline{ECAS} * \overline{CLK} * \overline{RESET}$

If (VCC)  $\overline{ECAS1} = \overline{IRDY} * \overline{CLK}$   
+  $\overline{ECAS1} * \overline{CLK}$

If (VCC)  $\overline{DOACC} = \overline{AREQ} * \overline{RFRQD} * \overline{IBREQ} * \overline{RESET}$   
+  $\overline{CS} * \overline{IREQ} * \overline{IREQH} * \overline{AREQ} * \overline{RESET}$   
+  $\overline{DOACC} * \overline{IRDY} * \overline{RESET}$

If (VCC)  $\overline{ENDACC} = \overline{IREQ} * \overline{IREQH}$   
+  $\overline{RFRQD} * \overline{IRDY}$   
+  $\overline{RFRQD} * \overline{AREQ} * \overline{IREQH}$   
+  $\overline{ENDACC} * \overline{AREQ}$   
+  $\overline{RESET}$

If (VCC)  $\overline{IREQH} = \overline{AREQ} * \overline{IREQ}$   
+  $\overline{IREQH} * \overline{AREQ} * \overline{RESET}$

If (VCC)  $\overline{IRDY1} = \overline{DTACK2} * \overline{AREQ} * \overline{IREQH}$   
+  $\overline{AREQ} * \overline{IRDY} * \overline{IREQH} * \overline{CLK} * \overline{DOACC}$   
+  $\overline{IRDY1} * \overline{IRDY} * \overline{AREQ}$

If (VCC)  $\overline{AREQ1} = \overline{CS} * \overline{IREQ} * \overline{IRDY} * \overline{ENDACC} * \overline{RESET}$   
+  $\overline{AREQ1} * \overline{ENDACC} * \overline{RESET}$   
+  $\overline{AREQ1} * \overline{DOACC} * \overline{RESET}$

#### Key: Reading PAL equations written in PLAN

EXAMPLE EQUATIONS:  $\overline{READ} = \overline{CS\_RD} * \overline{ADS1D} * \overline{CLKA}$   
+  $\overline{READ} * \overline{ADS1D}$   
+  $\overline{READ} * \overline{CLKA}$

This example reads: the output " $\overline{READ}$ " will transition low on the next rising " $\overline{CLK}$ " clock edge (given that one of the following conditions are valid a setup time before " $\overline{CLK}$ " transitions high);

1. the input " $\overline{CS\_RD}$ " is high AND the input " $\overline{ADS1D}$ " is high AND the input " $\overline{CLKA}$ " is low, OR
2. the output " $\overline{READ}$ " is low AND the input " $\overline{ADS1D}$ " is low, OR
3. the output " $\overline{READ}$ " is low AND the input " $\overline{CLKA}$ " is high

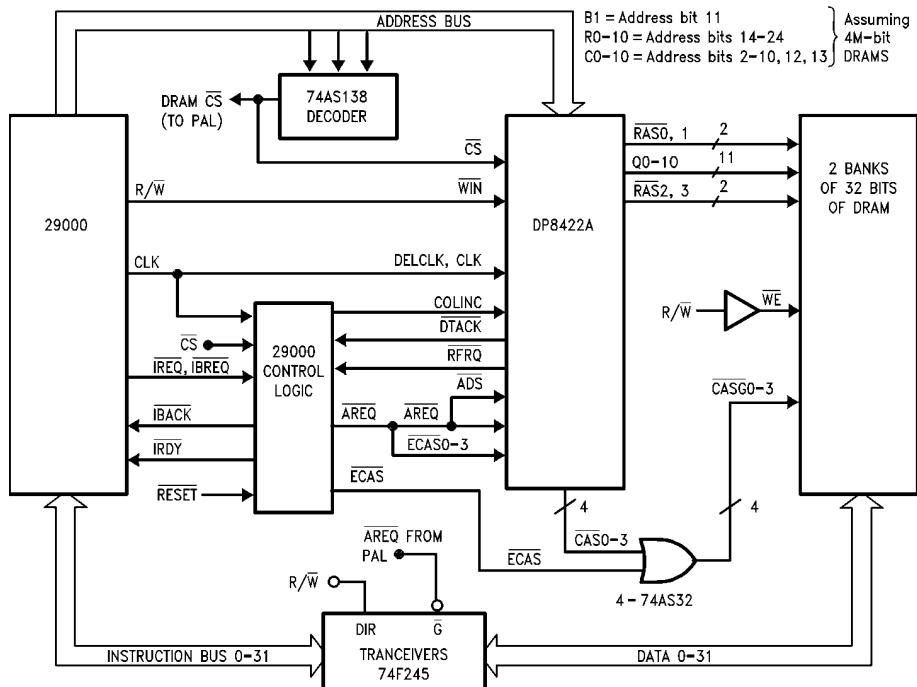
## V. 29000 application note PAL and 74AS374 outputs

What follows is a brief explanation of the PAL and 74AS374 outputs:

- AREQ1** This combinational output of the PAL is sampled at the next rising clock edge (74AS374) to provide the ADS and AREQ outputs that drive the DP8422A DRAM accesses. This output is held low to allow burst accessing until either a new access is requested by the 29000 (IREQ) or a refresh is requested (RFRQ).
- IRDY1** This combinational output of the PAL is sampled at the next rising clock edge (74AS374) to provide the IRDY output that terminates each 29000 access.
- IREQH** This combinational output of the PAL is used internal to the PAL as an indication of IREQ having transitioned high. It is useful in determining when the 29000 is terminating a burst access to request an access to another page (IREQH = IREQ = low).
- ENDACC** This combinational output of the PAL is used internal to the PAL as an indication of when to terminate a burst, or single, access. It indicates a new page access (IREQ), a refresh request (RFRQ), or a hardware reset (RESET) operation. Accesses are only terminated after IRDY is issued or during idle states when no accesses are pending.

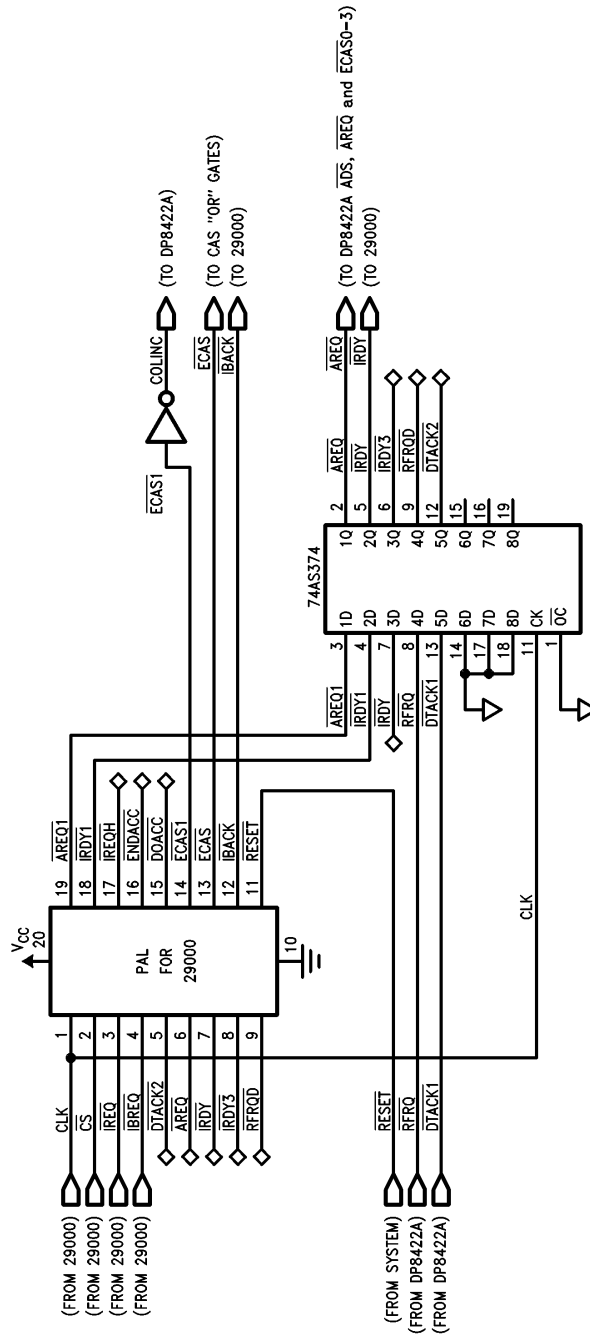
- DOACC** This combinational output of the PAL is used internal to the PAL to keep track of requested accesses, single (IREQ) or burst (IBREQ and IBACK).
- ECAS1** This combinational output of the PAL is used internal to the PAL to allow the ECAS output to have minimum delay following the CLK high and low.
- ECAS** This combinational output of the PAL is used to toggle the CAS outputs of the DP8422A during burst accessing.
- IBACK** This combinational output of the PAL is used as an input to the 29000 to indicate when the DP8422A is available to support burst accessing. This output is pulled high during refresh requests (RFRQ) and out of page accesses (IREQH = IREQ = low).
- AREQ** See AREQ1 explanation.
- IRDY** See IRDY1 explanation.
- IRDY3** This output (74AS374) is used as a state input to the PAL. This term is IRDY delayed by one clock period.
- RFRQD** This clocked output is used to synchronize the DP8422A RFRQ output.
- DTACK2** This clocked output is generated from the DP8422A DTACK1 output and is synchronized to the next rising clock edge.

**Block Diagram of 29000/DP8422A Design at 25 MHz (Instruction memory interface to Port A, Port B could be used as a data memory interface to load the instructions into the DRAM)**

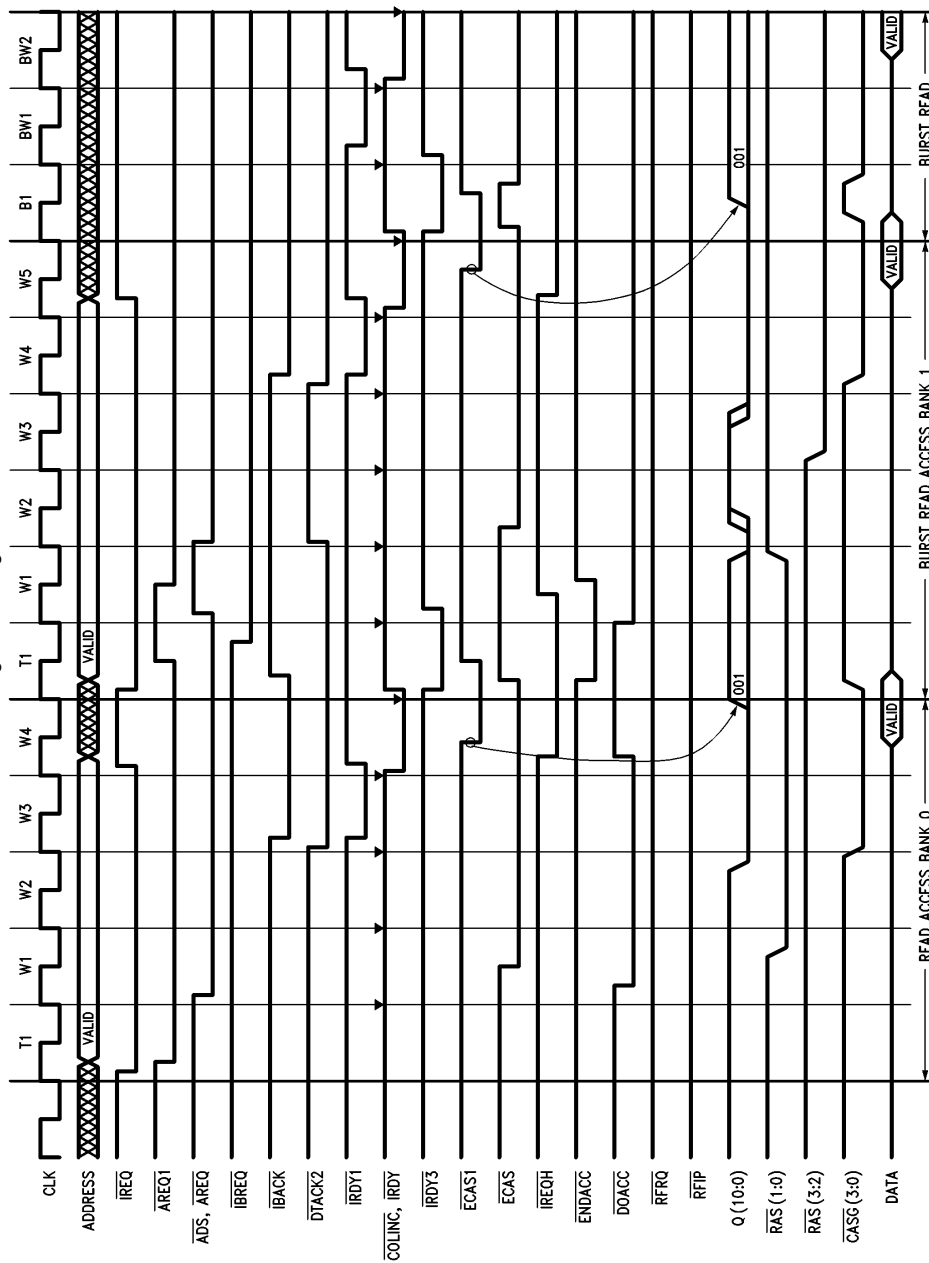


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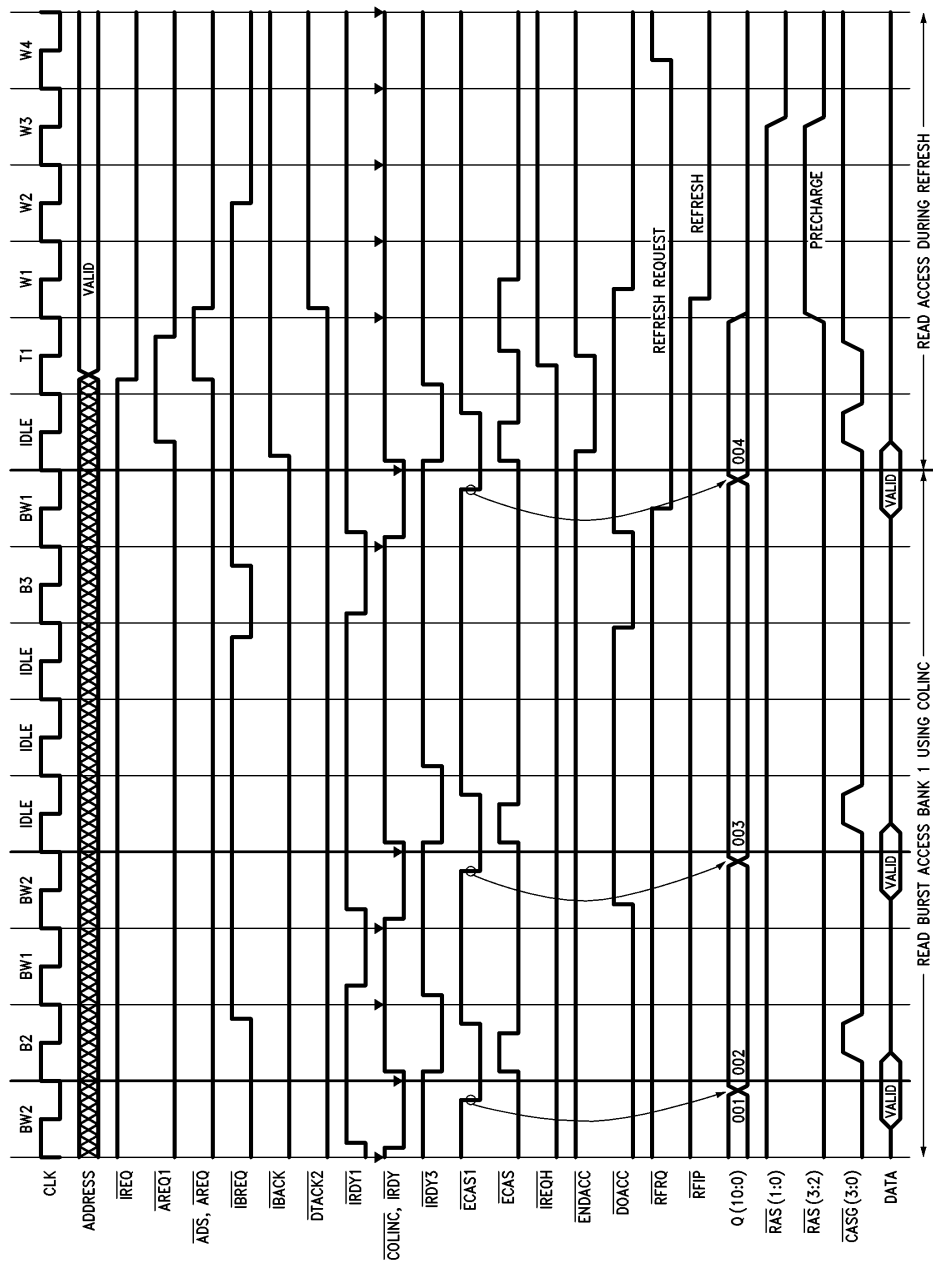
29000 Control Logic Block Diagram



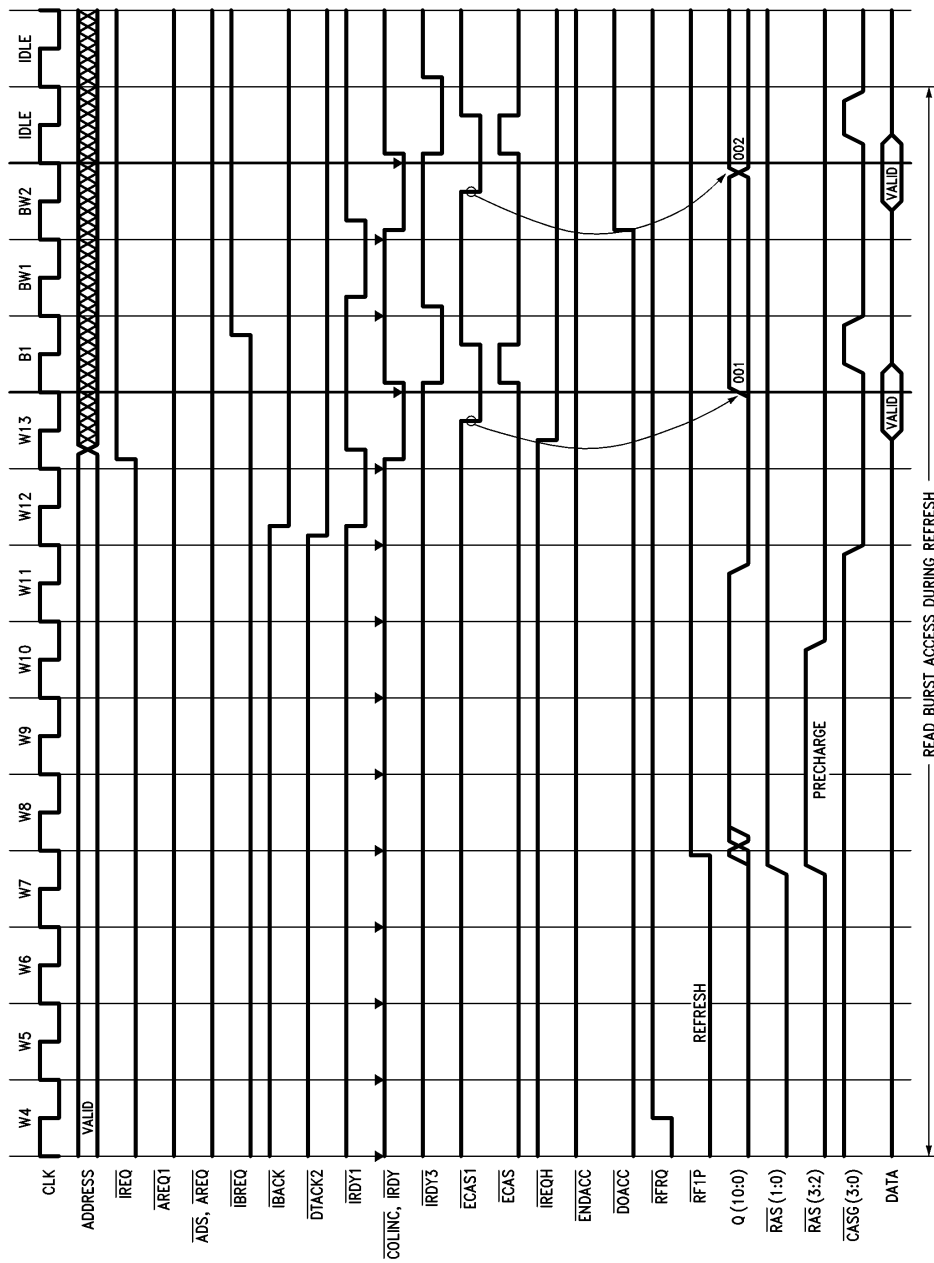
Design # 1 Timing



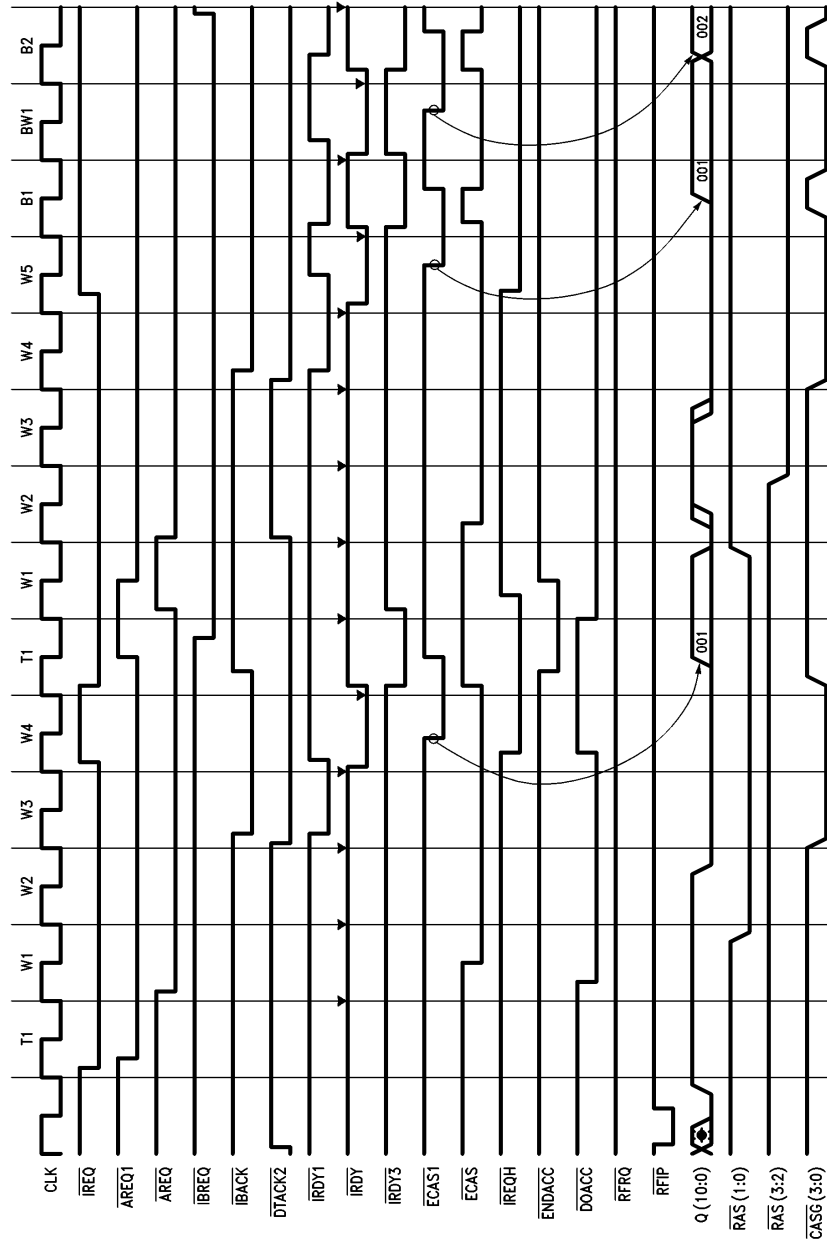
Design #1 Timing (Continued)



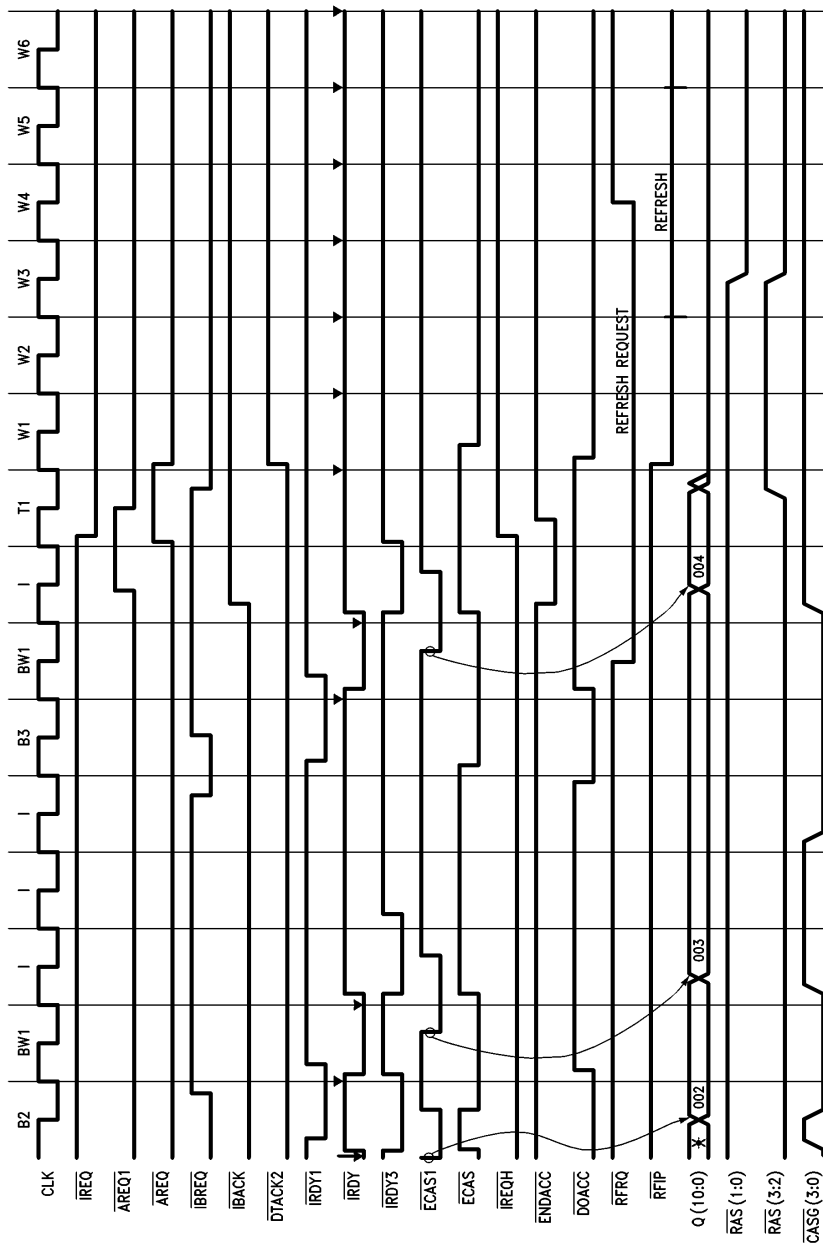
Design #1 Timing (Continued)



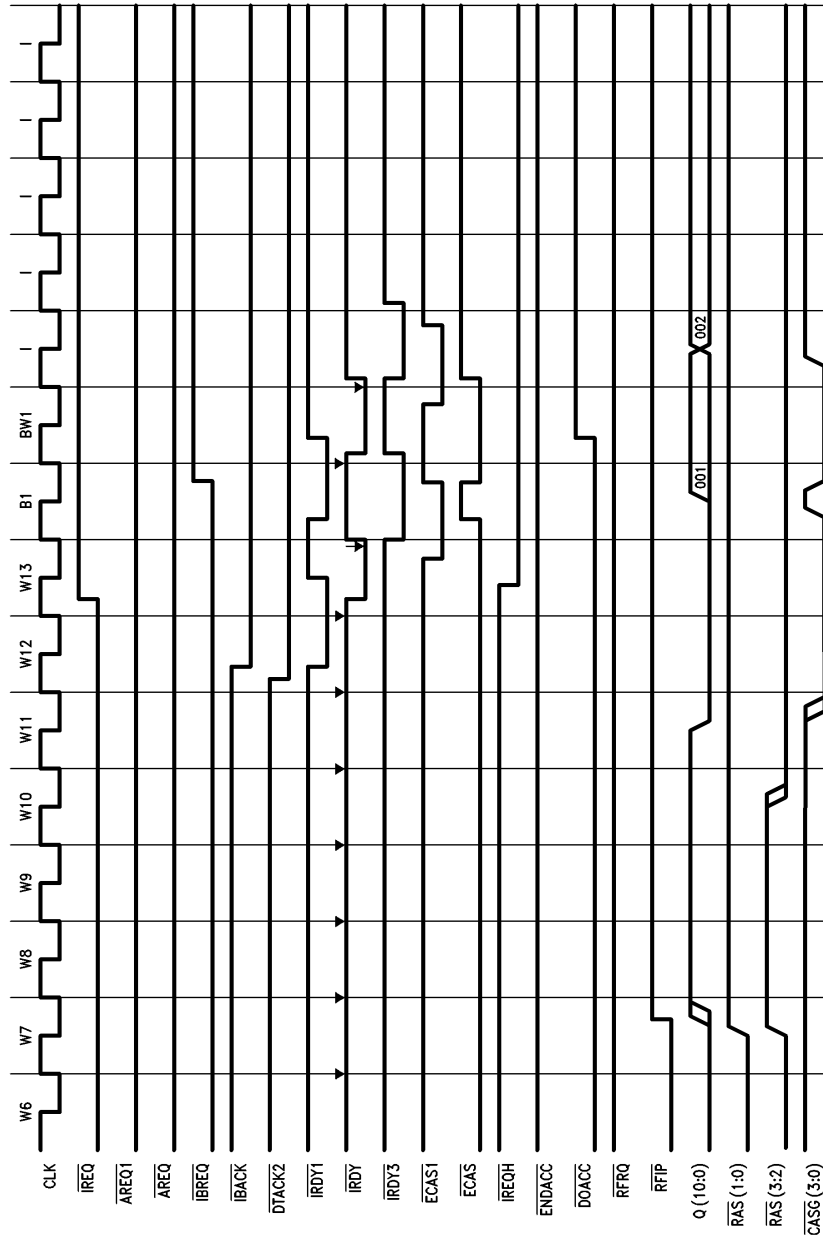
Design # 2 Timing

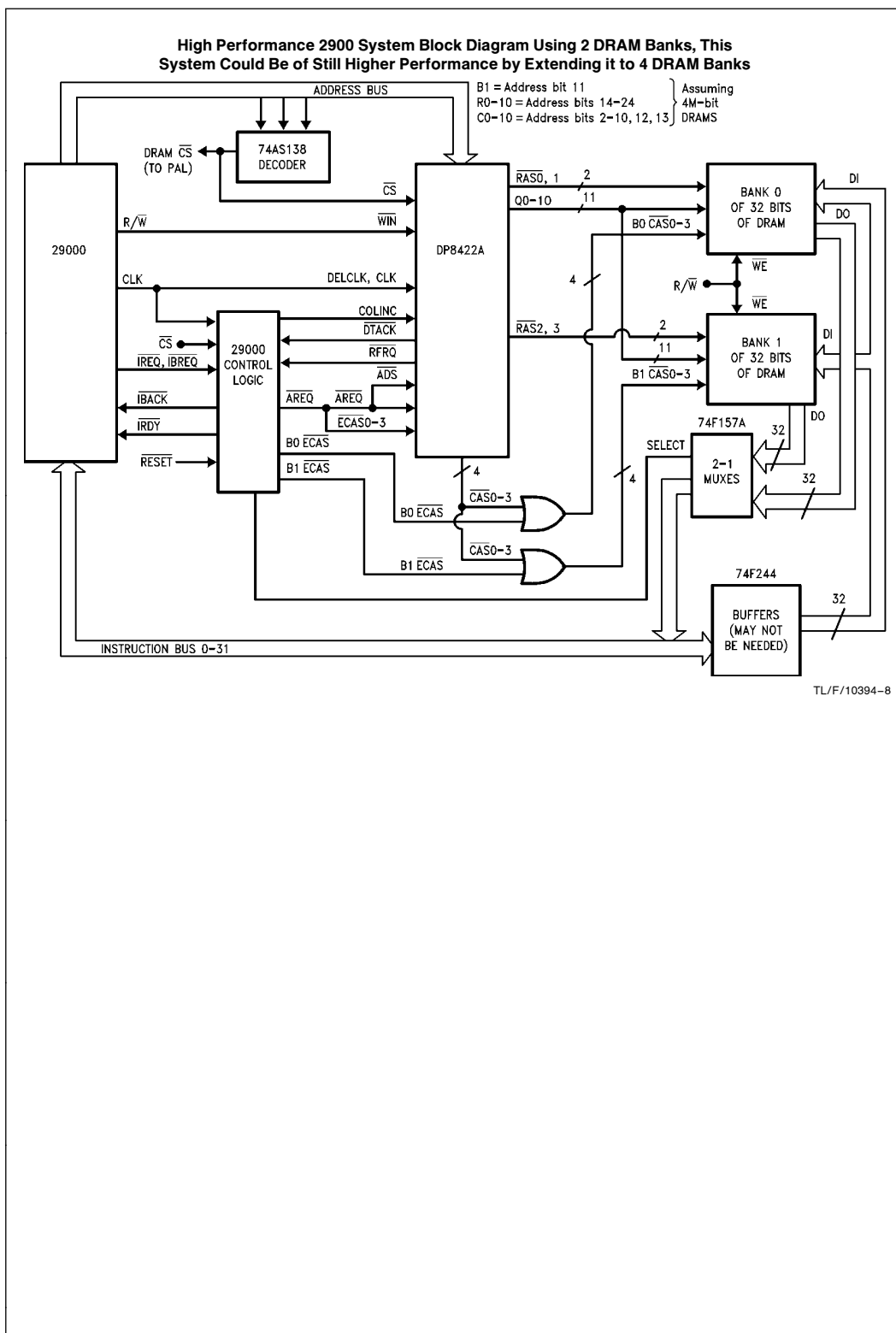


Design #2 Timing (Continued)

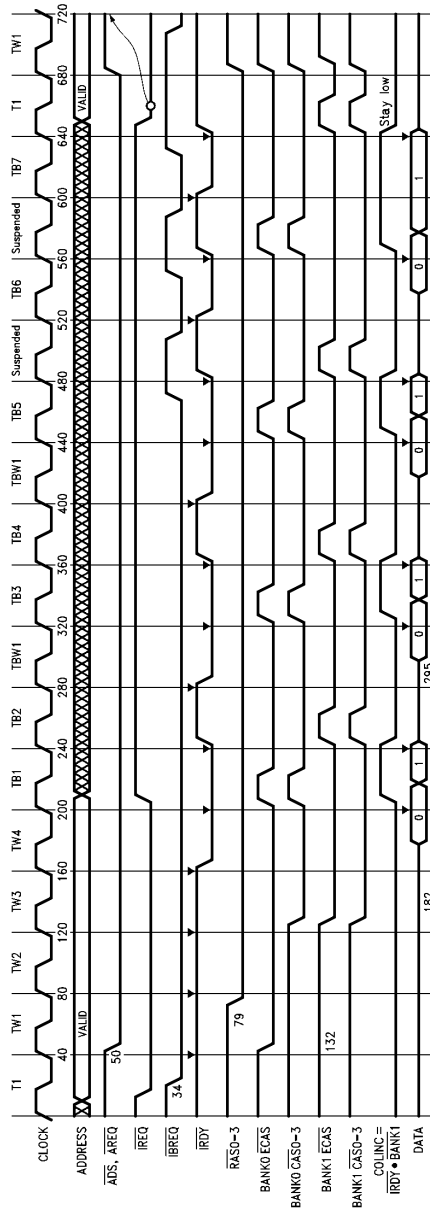


Design #2 Timing (Continued)



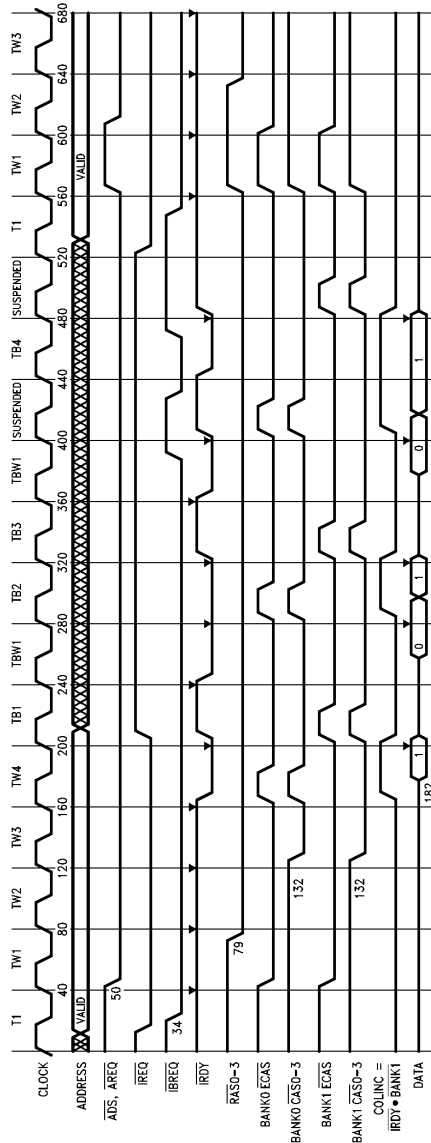


29000 Mode 1,2 Bank System High Performance (Start Access in Bank 0)



TL/F/10394-6

2900 Mode 1 2 Bank System High Performance (Start Access in Bank 1) (Interleaving Ability Not as Good)



TL/F/10394-7

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